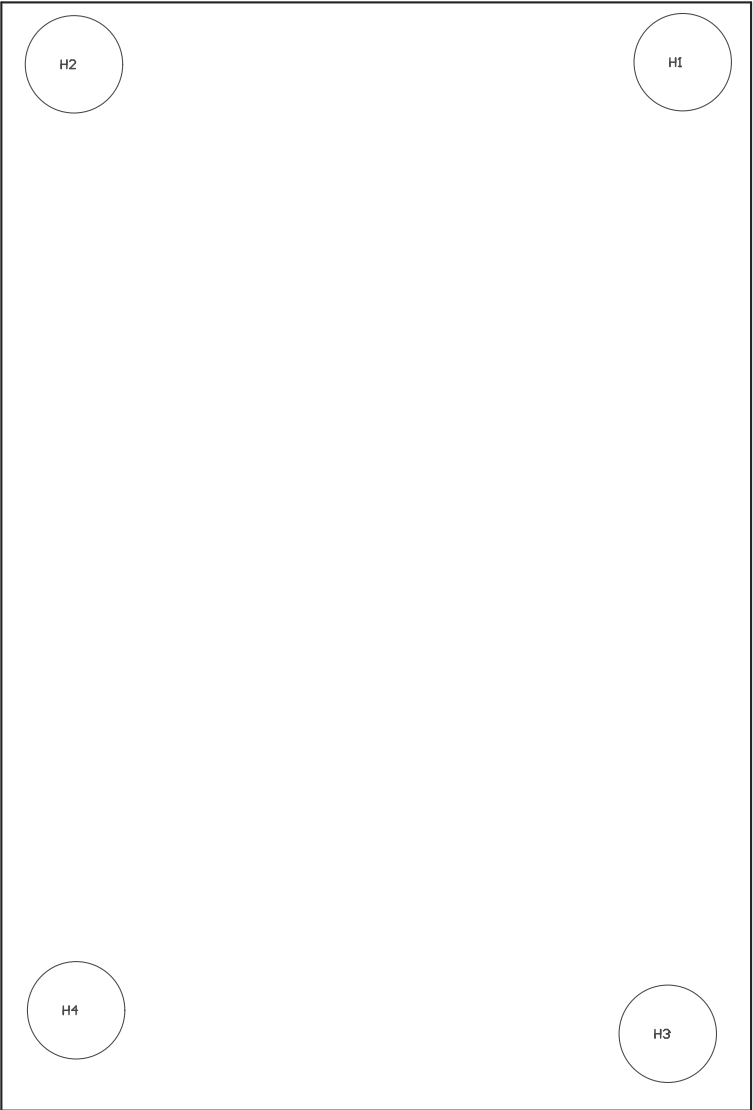


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01472	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01472		
PLOT NAME = Top Assembly Drawing	GENERATED : 5/11/2017 10:14:02 AM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01472	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01472		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 5/11/2017 10:14:04 AM	TEXAS INSTRUMENTS	

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